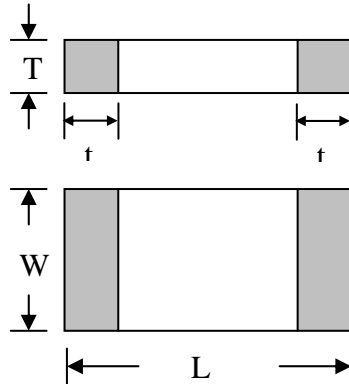
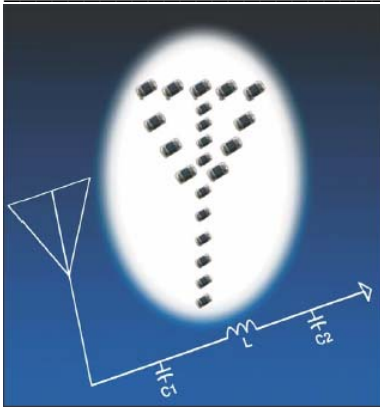




VCH4AG100R8MATWA



| Size (EIA) | | 0402 |
|-------------------|------------|-------------------------------|
| Length (L) | mm (in) | 1.00 ±0.10 (0.040 ± 0.004) |
| Width (W) | mm (in) | 0.50 ±0.10 (0.020 ±0.004) |
| Max Thickness (T) | mm (in) | 0.35 (0.014) |
| Terminal (t) | mm (in) | 0.25±0.15 (0.010±0.006) |

VCH4

AG

10

OR8

M

A

I

W

A

Varistor Chip
Chip Size
Thin 0402

Varistor Series
AntennaGuard

Working Voltage
10 = 10V

Capacitance Value
OR8 = 0.8pf

Tolerance
M = ±20%

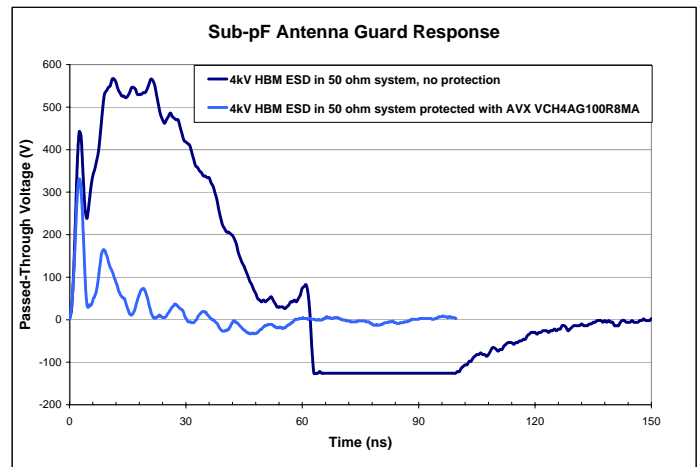
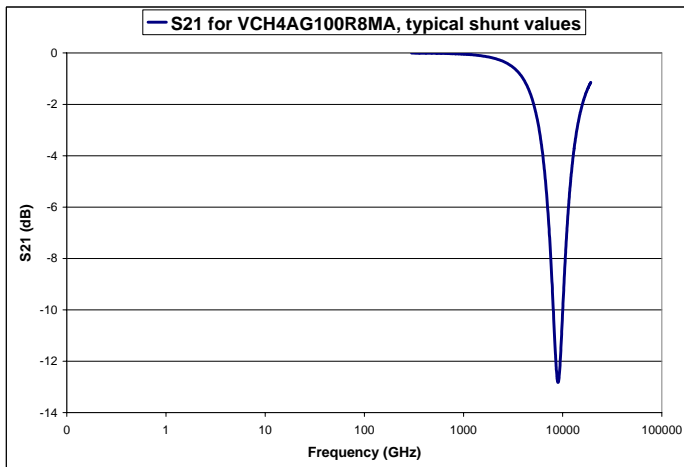
N/A Termination
T = Ni/Sn Alloy

Reel Size
W = 7"

Reel Qty
A = 4k

| AVX Part Number | V _w (DC) | V _B | I _L | Cap | Freq | Case Size |
|-----------------|---------------------|----------------|----------------|-----|------|-----------|
| VCH4AG100R8MA | ≤10 | 125 | <10 nA | 0.8 | M | 0402 |

- V_w(DC)** DC Working Voltage [V]
- V_B** Typical Breakdown Voltage [V @ 1mA_{DC}]
- I_L** Typical leakage current at the working voltage
- Cap** Typical capacitance [pF] @ frequency specified and 0.5V_{RMS}
- Freq** Frequency at which capacitance is measured [M = 1MHz]



| Parameter/Test | Requirement | Test method |
|-------------------------------|---|---|
| Operating Range | -55°C to +125° C | |
| Appearance/Dimensions | No visible damage Dimensions: see par. 6 | Visual examination at 10% magnification Dimensions verification by class2 caliper |
| Solderability | The dipped surface shall be at least 95% covered with a new smooth solder coating. | Soak in eutectic solder bath of temperature at 230+/-5°C for 5sec. |
| Solder Heat Resistance | No mechanical damage. Forward Breakdown voltage change shall not be more than ± 10% | <ul style="list-style-type: none"> a. Read forward breakdown voltage. b. Soak in eutectic solder bath of temperature at 260+/-5°C. for 10+/-1sec. c. Natural cool down to +25°C d. Read forward breakdown voltage after 24+/-2 hours. |
| ESD | IL @ RV <100nA | <ul style="list-style-type: none"> a. Read IL b. 1k pulses @ 8kV contact (8 X 20uS waveform) c. Read IL |
| Life Test | Forward breakdown voltage change shall not be more than ± 10% | <ul style="list-style-type: none"> a. Read forward breakdown voltage. b. Apply 100% of working voltage at test temperature of 125+/-4°C for 1,000+48/-0hours. c. Read forward breakdown voltage after 24+/-2 hours conditioning at 25+/-5°C |
| Termination Strength | All components must stay in place. | <ul style="list-style-type: none"> a. Solder components onto substrate. b. Apply 500 grams lateral force across the body of the component. |
| Thermal Shock | Forward breakdown voltage change shall not be more than ± 10% | <ul style="list-style-type: none"> Step 1: -55°C ± 2°C for 30 ± 3 min Step 2: Room temp for ≤ 3 min Step 3: +125°C ± 2°C for 30 ± 3 min Step 4: Room temp for ≤ 3 min Repeat for 100 cycles and measure after 24 hours at room temperature |